476-1859

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE APPLICATION OF	)
Philip Andrew Anslow et al.	)
SERIAL NO: To be assigned	)
FILED: Herewith	)
FOR: High Density Printed Wiring Board Having In-Via Surface Mounting Pads	)



3/a/ou M. Predge

## **CLAIM FOR PRIORITY**

Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

Dear Sir:

Under the International Convention, for the purposes of priority, applicant claims the benefit of the United Kingdom Application No. 9828656.0, filed December 23, 1998.

A certified copy of said application is appended hereto.

DATE: November 30, 1999

Respectfully submitted,

Registration No. 26,935

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## ARTIFACT SHEET

Indicate quantity of item(s) received by the USPTO but not scanned.

X	Priority Document No. 9828656.0 Country UK  Doc Code: FRPR
	CD(s) containing computer program listing Doc Code: Computer
	Stapled Set(s) of Extra Color Drawings Doc Code: Artifact
	CD(s) containing pages of specification and/or sequence listing Doc Code: Artifact
	CD(s) with content unspecified  Doe Code: Artifact
	Microfilm(s) Doe Code: Artifact
	Video tape(s)  Doc Code: Artifact
	Other mass storage media, description:  Doc Code: Artifact
	Model(s) Doc Code: Artifact
	Other, description:  Doc Code: Artifact
	Other, description:  Doc Code: Artifact
	Other, description:  Doc Code: Artifact